

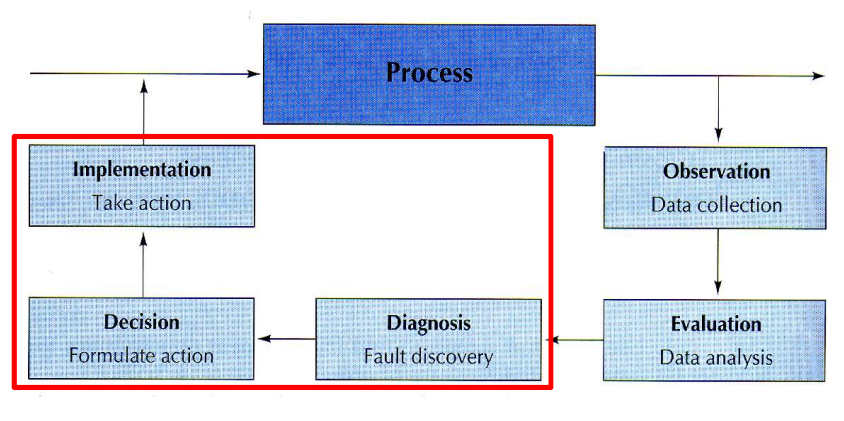
Corrective Actions and Process Capability Index

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Classical Control System View of SPC Implementation



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Closing Control Loop: Causes and Actions

- Step 1: Find the relevant causes/factors:
 - Scatter Plot
 - Regression Analysis and Classification Tree
 - Machine learning
- Step 2: Prioritize defects/causes
 - Pareto Diagram
- Step 3: Find the root causes
 - Cause-and-Effect Diagram
- Step 4: Close the control loop
 - Out-of-Control Action Plans (OCAPS)
 - Advanced Process Control (APC/Run-to-Run Control)

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Scatter Plot

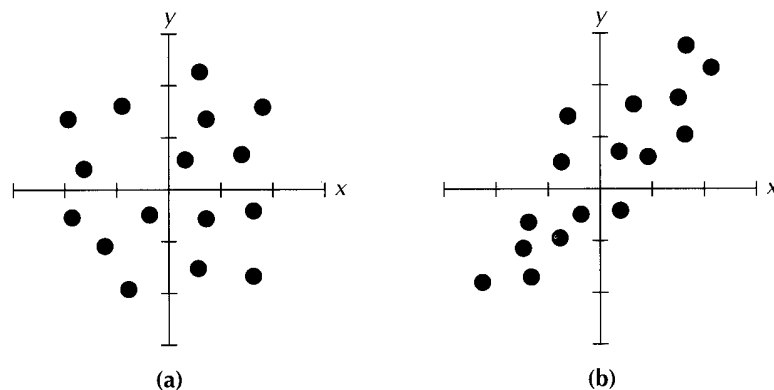


Figure 6.18 Examples of No Correlation (a) and Positive Correlation (b)

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Regression Analysis and Decision Trees Learning

- Regression analysis:
 - Simple and multiple regression will be covered
 - Stepwise, ridge, LASSO, etc.
- Decision trees: Data Mining courses
 - CART classification and Regression Tree
 - Gini Index/variance reduction
 - ID3/C4.5
 - Information Entropy/Information Gain/Information Gain Ratio
- Supervised machine learning

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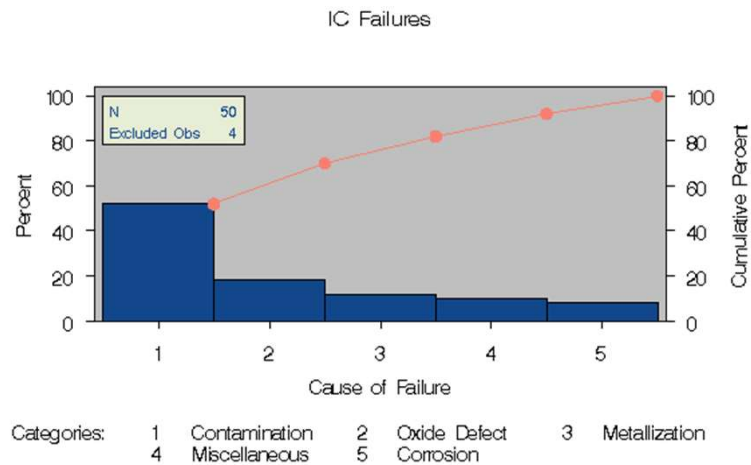
Pareto Principle

- Also known as the **80/20 rule**, the **law of the vital few**, or the principle of **factor sparsity**
- Named after Italian economist Vilfredo Pareto who noted the 80/20 connection by showing that approximately 80% of the land in Italy was owned by 20% of the population
- Axiom of business management: “80% of sales come from 20% of clients”
- In computer science, Microsoft noted that by fixing the top 20% of the most-reported bugs, 80% of the related errors and crashes in a given system would be eliminated.

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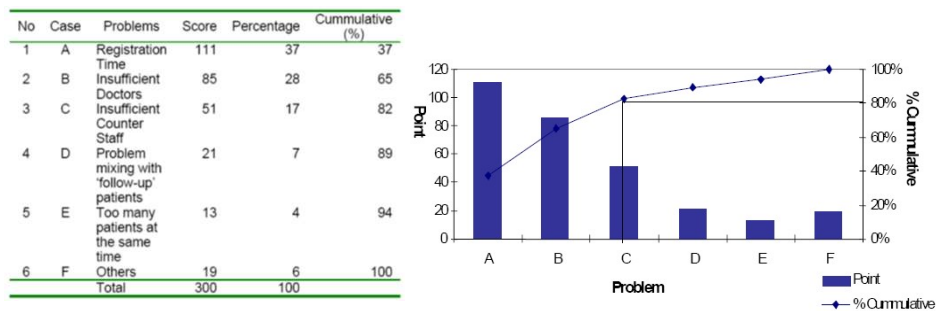
Pareto Diagram



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Pareto Diagram Example Long Waiting Time

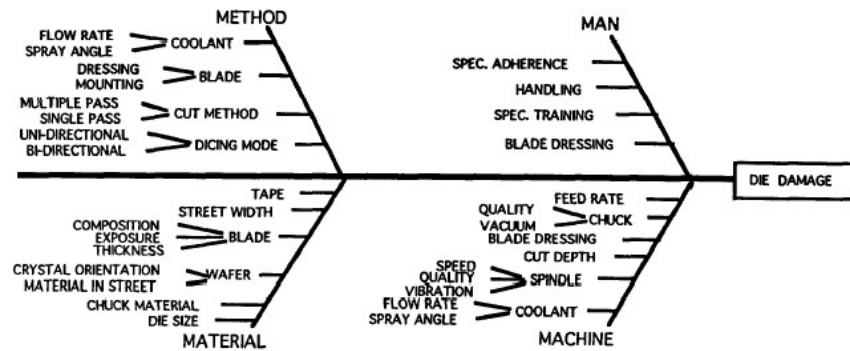


Source: Mohamad Hanaffi Abdullah, "Study on Outpatients' Waiting Time in Hospital Universiti Kebangsaan Malaysia (HUKM) Through the Six Sigma Approach"

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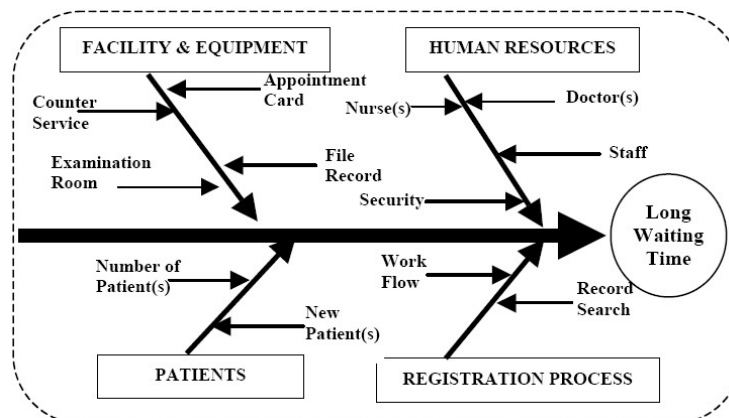
Cause-and-Effect (Ishikawa Fishbone) Diagram



Source: Harry Shah and Satish Ram, "CHARACTERIZATION OF THE WAFER DICING PROCESS USING TAGUCHI METHODOLOGY," IEEVSEMI Advanced Semiconductor Manufacturing Conference 9, 200-205, 1992

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Cause-and-Effect (Ishikawa Fishbone) Diagram Example – Long Waiting Time



Source: Mohamad Hanaffi Abdullah, "Study on Outpatients' Waiting Time in Hospital University Kebangsaan Malaysia (HUKM) Through the Six Sigma Approach"

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Taking Actions and Making Adjustments

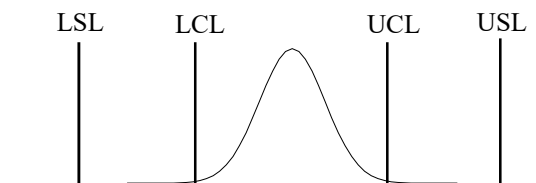
- **Out-of-Control Action Plans (OCAPS)**
 - Detail the action to be taken once an out-of-control situation is detected.
 - A specific flowchart, that leads the process engineer through the corrective procedure, may be provided for each unique process
- **Advanced Process Control:** Run-to-Run adjustments made to the process that are programmed to compensate for the size of the out-of-control measurement

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Process Capability Assessment

- What is a capable process?
- Assess process capability **in terms of control chart application**
- Comparing 6-s control window of \bar{X} -chart to the specification window:



$$C_p = \frac{USL - LSL}{6\sigma}$$

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Process Capability

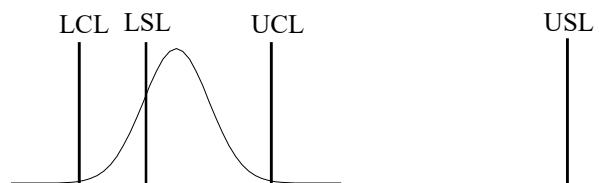
- The ability of the process to produce parts that conform to the engineering specifications (spec).
- A good process should
 - maintain a good statistical control
 - conform to engineering spec
- A process in statistical control but not meeting the spec?
 - the process is off-center from the nominal
 - the process variation is too large

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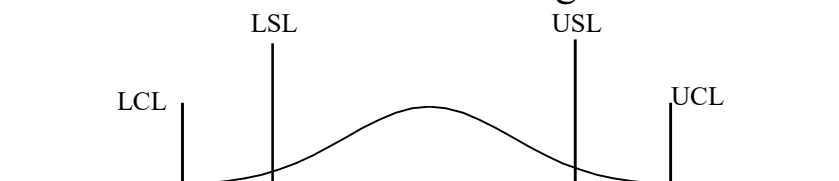
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Incapable Processes

- Process is off-center from the nominal



- Process variation is too large



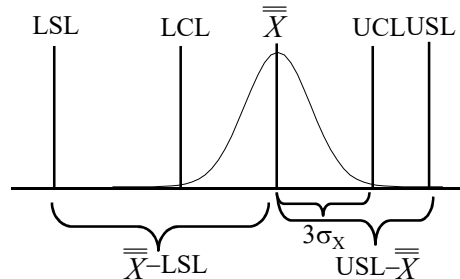
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Process Capability Index

$$C_p = \frac{USL - LSL}{6\sigma_X}$$

$$C_{pk} = \min \left[\frac{\bar{\bar{X}} - LSL}{3\sigma_X}, \frac{USL - \bar{\bar{X}}}{3\sigma_X} \right]$$



- **C_p index measures potential capability (variation)**
 C_{pk} index reflects the current process performance (mean and variation) and for process with asymmetric spec limits
- $C_{pk} \leq C_p$ [$C_{pk} = C_p$ when $\bar{\bar{X}} = (USL + LSL)/2$]

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Estimating C_p from Control Chart

- If a process is in statistical control,

$$C_p = \frac{USL - LSL}{6\hat{\sigma}_X} \quad \hat{\sigma}_X = s_x$$

- Example: $s_x = 0.00237$, $n=6$, spec=(0.253, 0.263)

$$\hat{\sigma}_X = s_x = 0.00237$$

$$C_p = \frac{USL - LSL}{6\hat{\sigma}_X} = \frac{0.263 - 0.253}{6 \cdot 0.00237} = 0.72$$

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An Integrated PCI - C_{pm}

$$C_{pm} = \frac{USL - LSL}{6\tilde{\sigma}}$$

$$\text{where } \tilde{\sigma} = \sqrt{E(X - T)^2} = \sqrt{\sigma^2 + (\mu - T)^2}$$

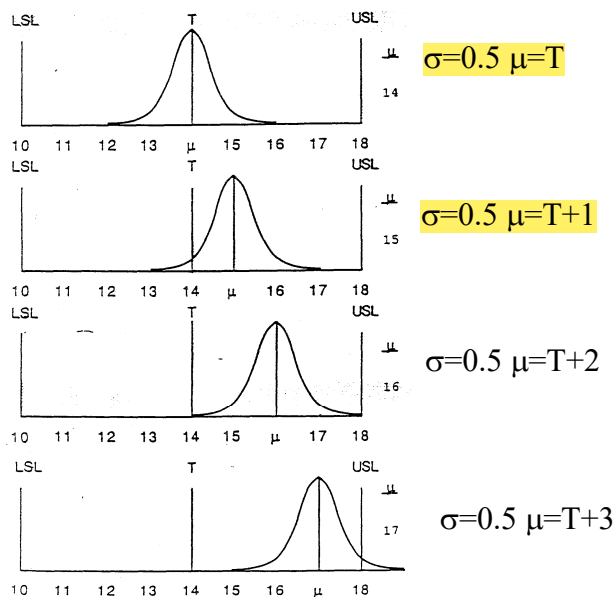
$$\hat{\tilde{\sigma}} = \sqrt{\frac{\sum_{i=1}^n (X_i - T)^2}{n}} = \sqrt{\hat{\sigma}^2 + (T - \bar{X})^2}$$

$$C_{pm}^* = \frac{\min[USL - T, T - LSL]}{3\tilde{\sigma}}$$

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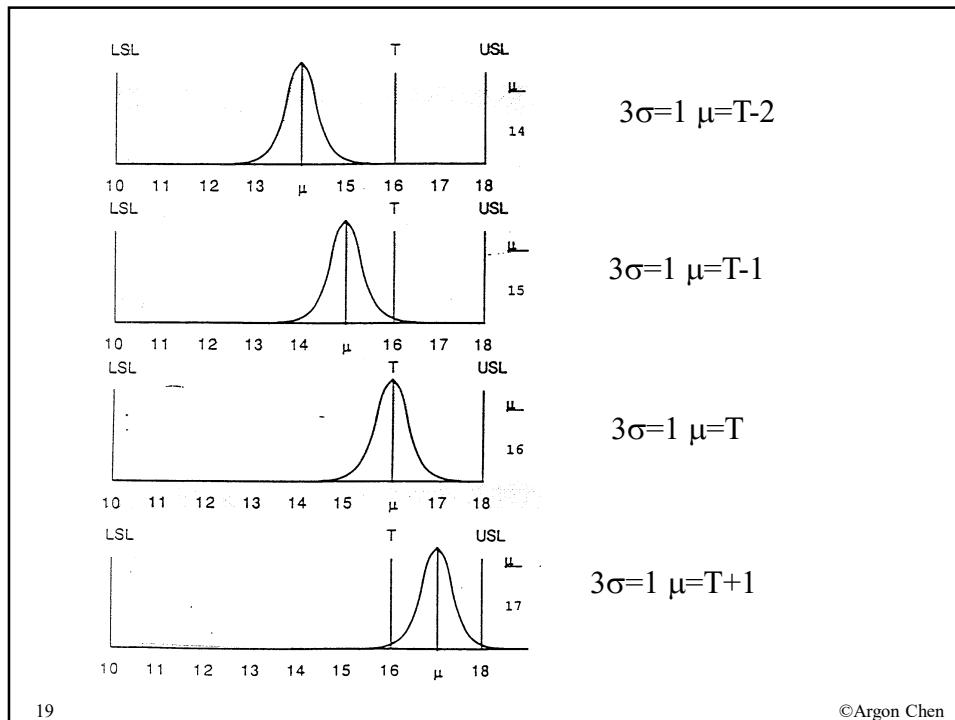
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Comparison of PCI's



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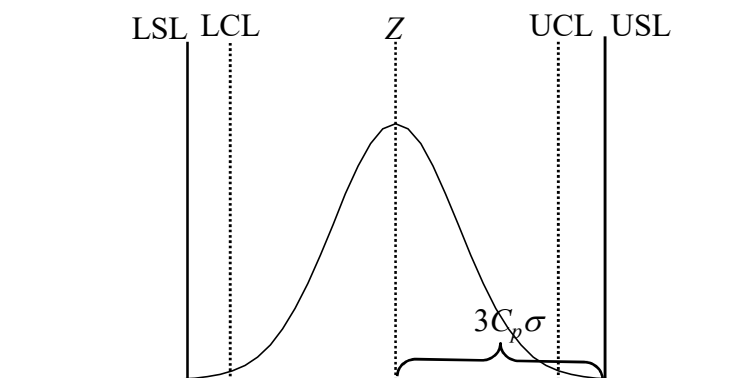


Calculation of Out-of-Spec %


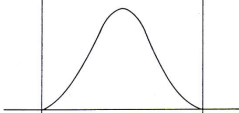
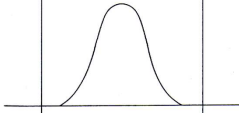
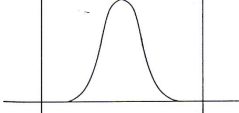
Assuming normally distributed X : $Z = \frac{X - \bar{X}}{\hat{\sigma}_X} \sim N(0,1)$

When $\bar{X} = (LSL + USL)/2$

$$\begin{aligned} \text{Out-of-spec \%} &= [P(X \geq USL) + P(X \leq LSL)] \times 100\% \\ &= [P(Z \geq 3C_p) + P(Z \leq -3C_p)] \times 100\% \end{aligned}$$



Four Examples of Process Capability

Process	C_p	Total amount outside limits	Typical actions to be taken
	< 1.0	$\approx 5.0\%$	Heavy process control, sorting, rework, etc.
	1.0	0.3%	Heavy process control, inspection
	1.33	64 ppm	Reduced inspection, selected use of control charts
	1.63	1 ppm	Spot checking, selected use of control charts

ppm: parts per million

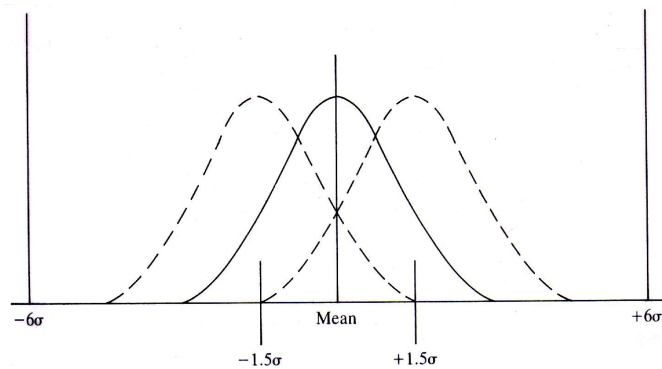
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Six- σ Concept of Process Capability

$$C_p = 2$$

If mean shifts $\pm 1.5\sigma$, only 3.4 ppm will be beyond spec limits.



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How to improve C_{pk} ?

- Reduce variation
 - remove special variation (SPC)
 - reduce common variation (process improvement, robust design)

- Adjust mean to nominal value

If $\sigma_x = 10$ then

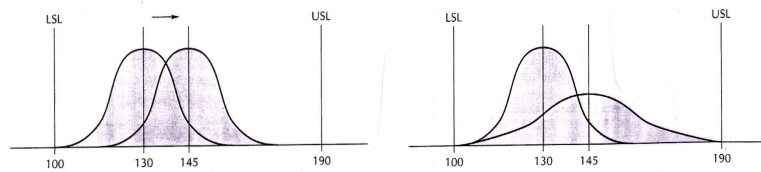
$C_{pk} = 1.0$ (mean = 130)

$C_{pk} = 1.5$ (mean = 145)

mean = 145, $\sigma_x = 15$

mean = 130, $\sigma_x = 10$

then $C_{pk} = 1.0$



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Steps in Assessment of Process Capability

- estimate $\sigma_x = s_x$
- calculate C_p , C_{pk}
- calculate out-of-spec percentage using

$$Z = \frac{X - \bar{\bar{X}}}{\hat{\sigma}_X}$$

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Example: Poly CVD Process

	CD_site1	CD_site2	CD_site3	CD_site4	CD_site5	within-wafer average	within-wafer stdev
wafer 1	60.52	59.84	59.34	60.62	59.59	59.98	0.57
wafer 2	61.11	60.23	60.08	61.04	60.07	60.50	0.52
wafer 3	60.43	60.09	59.58	59.67	59.67	59.89	0.36
wafer 4	60.46	60.16	59.51	60.53	59.50	60.03	0.50
wafer 5	61.08	60.10	59.87	61.02	60.17	60.45	0.56
wafer 6	60.73	60.66	59.89	60.12	60.03	60.29	0.38
wafer 7	60.17	59.46	58.84	60.26	59.64	59.67	0.58
wafer 8	60.52	59.73	59.35	60.47	59.78	59.97	0.51
wafer 9	60.28	60.02	59.15	59.59	59.39	59.69	0.46
wafer 10	60.22	59.81	59.19	60.52	59.82	59.91	0.50
wafer 11	60.61	59.69	59.51	60.46	59.69	59.99	0.50
wafer 12	60.06	60.00	59.28	59.55	59.43	59.67	0.35
wafer 13	60.37	59.93	59.15	60.49	59.71	59.93	0.54
wafer 14	60.77	60.02	59.97	60.84	59.77	60.27	0.49
wafer 15	60.22	59.92	59.12	59.58	59.63	59.69	0.41
wafer 16	60.13	59.73	59.07	60.59	60.04	59.91	0.56
wafer 17	60.82	60.13	59.63	60.74	59.72	60.21	0.56
wafer 18	60.60	60.57	59.84	60.22	60.03	60.25	0.33
wafer 19	60.15	59.48	59.07	60.29	59.44	59.69	0.51
wafer 20	60.73	60.00	59.58	60.83	60.11	60.25	0.52
wafer 21	60.44	60.28	59.37	59.85	59.67	59.92	0.44
wafer 22	60.56	60.23	59.59	60.63	59.58	60.12	0.51
wafer 23	60.55	59.66	59.53	60.44	59.72	59.98	0.48
wafer 24	60.18	60.16	59.46	59.83	59.58	59.84	0.33
wafer 25	60.47	59.75	59.23	60.38	59.58	59.88	0.53
wafer 26	60.22	59.79	59.20	60.15	59.47	59.77	0.44
wafer 27	60.68	60.03	59.68	60.69	59.75	60.17	0.49
wafer 28	60.29	60.54	59.43	59.75	60.00	60.00	0.44
wafer 29	60.13	59.53	58.83	60.11	59.31	59.58	0.55
wafer 30	60.33	59.69	59.60	60.40	59.73	59.95	0.38
site average	60.46	59.97	59.43	60.32	59.72		
wafer-to-wafer site Stdev	0.27	0.31	0.32	0.43	0.23		

USL=62

LSL=58

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Overall Process Capability

$$\hat{\sigma}_x = s_x = 0.49$$

$$C_p = \frac{USL - LSL}{6\sigma_x} = \frac{62 - 58}{6 \cdot 0.49} = 1.36$$

$$C_{pk} = \min \left[\frac{\bar{\bar{X}} - LSL}{3\sigma_x}, \frac{USL - \bar{\bar{X}}}{3\sigma_x} \right] = \min \left[\frac{59.98 - 58}{3 \cdot 0.49}, \frac{62 - 59.98}{3 \cdot 0.49} \right] = 1.347$$

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Out-of-Spec Calculation

- $Z_L = \frac{LSL - \bar{X}}{\sigma_x} = \frac{58 - 59.98}{0.49} = -4.041 \Rightarrow P(X \leq 58) \text{ is } \Psi(-4.041) = 2.66E-5$
- $Z_U = \frac{USL - \bar{X}}{\sigma_x} = \frac{62 - 59.98}{0.49} = 4.122 \Rightarrow P(X \geq 62) \text{ is } 1 - \Psi(4.122) = 1.88E-5$
- out-of-spec percentage = $2.66E-5 + 1.88E-5 = 4.54E-5 = 0.0045\%$

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Site-1 Process Capability

$$\hat{\sigma}_x = s_{\text{site-1}} = 0.27$$

$$C_p = \frac{USL - LSL}{6\sigma_x} = \frac{62 - 58}{6 \cdot 0.27} = 2.47$$

$$C_{pk} = \min \left[\frac{\bar{X} - LSL}{3\sigma_x}, \frac{USL - \bar{X}}{3\sigma_x} \right] = \min \left[\frac{60.46 - 58}{3 \cdot 0.27}, \frac{62 - 60.46}{3 \cdot 0.27} \right] = 1.9$$

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